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Details	
Product Status	Obsolete
Number of LABs/CLBs	1846
Number of Logic Elements/Cells	18460
Total RAM Bits	1669248
Number of I/O	361
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	484-BBGA, FCBGA
Supplier Device Package	484-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep1s20f484c5

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About This Handbook

This handbook provides comprehensive information about the Altera® Stratix family of devices.

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Typographic Conventions

This document uses the typographic conventions shown below.

Visual Cue	Meaning
Bold Type with Initial Capital Letters	Command names, dialog box titles, checkbox options, and dialog box options are shown in bold, initial capital letters. Example: Save As dialog box.
bold type	External timing parameters, directory names, project names, disk drive names, filenames, filename extensions, and software utility names are shown in bold type. Examples: f _{MAX} , \qdesigns directory, d: drive, chiptrip.gdf file.
Italic Type with Initial Capital Letters	Document titles are shown in italic type with initial capital letters. Example: AN 75: High-Speed Board Designs.
Italic type	Internal timing parameters and variables are shown in italic type. Examples: t_{PlA} , $n+1$.
	Variable names are enclosed in angle brackets (< >) and shown in italic type. Example: <file name="">, <pre><pre><pre></pre></pre></pre></file>
Initial Capital Letters	Keyboard keys and menu names are shown with initial capital letters. Examples: Delete key, the Options menu.
"Subheading Title"	References to sections within a document and titles of on-line help topics are shown in quotation marks. Example: "Typographic Conventions."
Courier type	Signal and port names are shown in lowercase Courier type. Examples: $\mathtt{data1}$, \mathtt{tdi} , \mathtt{input} . Active-low signals are denoted by suffix \mathtt{n} , $\mathtt{e.g.}$, \mathtt{resetn} .
	Anything that must be typed exactly as it appears is shown in Courier type. For example: c:\qdesigns\tutorial\chiptrip.gdf. Also, sections of an actual file, such as a Report File, references to parts of files (e.g., the AHDL keyword SUBDESIGN), as well as logic function names (e.g., TRI) are shown in Courier.
1., 2., 3., and a., b., c., etc.	Numbered steps are used in a list of items when the sequence of the items is important, such as the steps listed in a procedure.
• •	Bullets are used in a list of items when the sequence of the items is not important.
✓	The checkmark indicates a procedure that consists of one step only.
	The hand points to information that requires special attention.
4	The angled arrow indicates you should press the Enter key.
	The feet direct you to more information on a particular topic.

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Table 1–1. Stratix Device Features — EP1S10, EP1S20, EP1S25, EP1S30							
Feature	EP1S10	EP1S20	EP1S25	EP1S30			
LEs	10,570	18,460	25,660	32,470			
M512 RAM blocks (32 × 18 bits)	94	194	224	295			
M4K RAM blocks (128 × 36 bits)	60	82	138	171			
M-RAM blocks (4K × 144 bits)	1	2	2	4			
Total RAM bits	920,448	1,669,248	1,944,576	3,317,184			
DSP blocks	6	10	10	12			
Embedded multipliers (1)	48	80	80	96			
PLLs	6	6	6	10			
Maximum user I/O pins	426	586	706	726			

Table 1–2. Stratix Device Features — EP1S40, EP1S60, EP1S80						
Feature	EP1S40	EP1S60	EP1S80			
LEs	41,250	57,120	79,040			
M512 RAM blocks (32 × 18 bits)	384	574	767			
M4K RAM blocks (128 × 36 bits)	183	292	364			
M-RAM blocks (4K × 144 bits)	4	6	9			
Total RAM bits	3,423,744	5,215,104	7,427,520			
DSP blocks	14	18	22			
Embedded multipliers (1)	112	144	176			
PLLs	12	12	12			
Maximum user I/O pins	822	1,022	1,238			

Note to Tables 1–1 and 1–2:

⁽¹⁾ This parameter lists the total number of 9×9 -bit multipliers for each device. For the total number of 18×18 -bit multipliers per device, divide the total number of 9×9 -bit multipliers by 2. For the total number of 36×36 -bit multipliers per device, divide the total number of 9×9 -bit multipliers by 8.

Table 2–2 shows the Stratix device's routing scheme.

Table 2–2. Strat	ix De	vice F	Routin	ng Scl	heme												
		Destination															
Source	LUT Chain	Register Chain	Local Interconnect	Direct Link Interconnect	R4 Interconnect	R8 Interconnect	R24 Interconnect	C4 Interconnect	C8 Interconnect	C16 Interconnect	TE	M512 RAM Block	M4K RAM Block	M-RAM Block	DSP Blocks	Column 10E	Row IOE
LUT Chain											>						
Register Chain											\						
Local Interconnect											✓	✓	✓	✓	✓	✓	\
Direct Link Interconnect			✓														
R4 Interconnect			✓		✓		✓	✓		✓							
R8 Interconnect			✓			✓			✓								
R24 Interconnect					✓		~	✓		✓							
C4 Interconnect			✓		✓			✓									
C8 Interconnect			✓			✓			✓								
C16 Interconnect					✓		\	\		✓							
LE	✓	✓	✓	✓	✓	✓		✓	✓								
M512 RAM Block			✓	✓	✓	✓		\	✓								
M4K RAM Block			✓	✓	✓	✓		✓	✓								
M-RAM Block								✓	✓								
DSP Blocks			✓	✓	✓	✓		✓	✓								
Column IOE				✓				✓	✓	✓							
Row IOE				✓		✓	✓	✓	✓	✓							

Read/Write Clock Mode

The memory blocks implement read/write clock mode for simple dual-port memory. You can use up to two clocks in this mode. The write clock controls the block's data inputs, wraddress, and wren. The read clock controls the data output, rdaddress, and rden. The memory blocks support independent clock enables for each clock and asynchronous clear signals for the read- and write-side registers. Figure 2–27 shows a memory block in read/write clock mode.

single DSP block can implement two sums or differences from two 18×18 -bit multipliers each or four sums or differences from two 9×9 -bit multipliers each.

You can use the two-multipliers adder mode for complex multiplications, which are written as:

$$(a+jb)\times(c+jd) = [(a\times c) - (b\times d)] + j\times[(a\times d) + (b\times c)]$$

The two-multipliers adder mode allows a single DSP block to calculate the real part $[(a \times c) - (b \times d)]$ using one subtractor and the imaginary part $[(a \times d) + (b \times c)]$ using one adder, for data widths up to 18 bits. Two complex multiplications are possible for data widths up to 9 bits using four adder/subtractor/accumulator blocks. Figure 2–38 shows an 18-bit two-multipliers adder.

Figure 2–38. Two-Multipliers Adder Mode Implementing Complex Multiply

Four-Multipliers Adder Mode

In the four-multipliers adder mode, the DSP block adds the results of two first -stage adder/subtractor blocks. One sum of four 18×18 -bit multipliers or two different sums of two sets of four 9×9 -bit multipliers can be implemented in a single DSP block. The product width for each multiplier must be the same size. The four-multipliers adder mode is useful for FIR filter applications. Figure 2–39 shows the four multipliers adder mode.

clock signals are routed from LAB row clocks and are generated from specific LAB rows at the DSP block interface. The LAB row source for control signals, data inputs, and outputs is shown in Table 2–17.

Table 2-17. D	Table 2–17. DSP Block Signal Sources & Destinations					
LAB Row at Interface	Control Signals Generated	Data Inputs	Data Outputs			
1	signa	A1[170]	OA[170]			
2	aclr0 accum_sload0	B1[170]	OB[170]			
3	addnsub1 clock0 ena0	A2[170]	OC[170]			
4	aclr1 clock1 ena1	B2[170]	OD[170]			
5	aclr2 clock2 ena2	A3[170]	OE[170]			
6	sign_b clock3 ena3	B3[170]	OF[170]			
7	clear3 accum_sload1	A4[170]	OG[170]			
8	addnsub3	B4[170]	OH[170]			

PLLs & Clock Networks

Stratix devices provide a hierarchical clock structure and multiple PLLs with advanced features. The large number of clocking resources in combination with the clock synthesis precision provided by enhanced and fast PLLs provides a complete clock management solution.

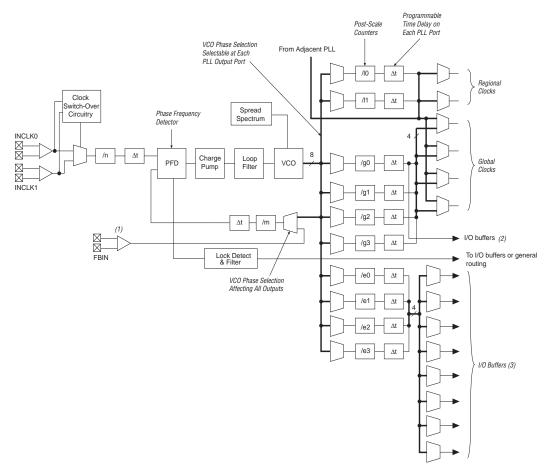
Global & Hierarchical Clocking

Stratix devices provide 16 dedicated global clock networks, 16 regional clock networks (four per device quadrant), and 8 dedicated fast regional clock networks (for EP1S10, EP1S20, and EP1S25 devices), and 16 dedicated fast regional clock networks (for EP1S30 EP1S40, and EP1S60, and EP1S80 devices). These clocks are organized into a hierarchical clock structure that allows for up to 22 clocks per device region with low skew and delay. This hierarchical clocking scheme provides up to 48 unique clock domains within Stratix devices.

Enhanced PLLs

Stratix devices contain up to four enhanced PLLs with advanced clock management features. Figure 2–52 shows a diagram of the enhanced PLL.

Figure 2-52. Stratix Enhanced PLL



Notes to Figure 2-52:

- (1) External feedback is available in PLLs 5 and 6.
- (2) This single-ended external output is available from the g0 counter for PLLs 11 and 12.
- (3) These four counters and external outputs are available in PLLs 5 and 6.
- (4) This connection is only available on EP1S40 and larger Stratix devices. For example, PLLs 5 and 11 are adjacent and PLLs 6 and 12 are adjacent. The EP1S40 device in the 780-pin FineLine BGA package does not support PLLs 11 and 12.

VCO period from up to eight taps for individual fine step selection. Also, each clock output counter can use a unique initial count setting to achieve individual coarse shift selection in steps of one VCO period. The combination of coarse and fine shifts allows phase shifting for the entire input clock period.

The equation to determine the precision of the phase shifting in degrees is: 45° ÷ post-scale counter value. Therefore, the maximum step size is 45° , and smaller steps are possible depending on the multiplication and division ratio necessary on the output counter port.

This type of phase shift provides the highest precision since it is the least sensitive to process, supply, and temperature variation.

Clock Delay

In addition to the phase shift feature, the ability to fine tune the Δt clock delay provides advanced time delay shift control on each of the four PLL outputs. There are time delays for each post-scale counter (e, g, or l) from the PLL, the n counter, and m counter. Each of these can shift in 250-ps increments for a range of 3.0 ns. The m delay shifts all outputs earlier in time, while n delay shifts all outputs later in time. Individual delays on post-scale counters (e, g, and l) provide positive delay for each output. Table 2–21 shows the combined delay for each output for normal or zero delay buffer mode where Δt_e , Δt_o , or Δt_l is unique for each PLL output.

The t_{OUTPUT} for a single output can range from -3 ns to +6 ns. The total delay shift difference between any two PLL outputs, however, must be less than ± 3 ns. For example, shifts on two outputs of -1 and +2 ns is allowed, but not -1 and +2.5 ns because these shifts would result in a difference of 3.5 ns. If the design uses external feedback, the Δt_e delay will remove delay from outputs, represented by a negative sign (see Table 2–21). This effect occurs because the Δt_e delay is then part of the feedback loop.

Table 2–21. Output Clock Delay for Enhanced PLLs				
Normal or Zero Delay Buffer Mode External Feedback Mode				
$\begin{split} \Delta t_{e \text{OUTPUT}} &= \Delta t_n - \!\!\! \Delta t_m + \Delta t_e \\ \Delta t_{g \text{OUTPUT}} &= \Delta t_n - \!\!\! \Delta t_m + \Delta t_g \\ \Delta t_{l \text{OUTPUT}} &= \Delta t_n - \!\!\! \Delta t_m + \Delta t_l \end{split}$	$\begin{split} \Delta \mathbf{t}_{\text{OUTPUT}} &= \Delta \mathbf{t}_{n} - \Delta \mathbf{t}_{m} - \Delta \mathbf{t}_{e} \ (1) \\ \Delta \mathbf{t}_{\text{gOUTPUT}} &= \Delta \mathbf{t}_{n} - \Delta \mathbf{t}_{m} + \Delta \mathbf{t}_{g} \\ \Delta \mathbf{t}_{\text{DUTPUT}} &= \Delta \mathbf{t}_{n} - \Delta \mathbf{t}_{m} + \Delta \mathbf{t}_{l} \end{split}$			

Note to Table 2-21:

(1) Δt_e removes delay from outputs in external feedback mode.

Table 2-27.	Table 2–27. DQS & DQ Bus Mode Support (Part 2 of 2) Note (1)					
Device	Package	Number of ×8 Groups	Number of ×16 Groups	Number of ×32 Groups		
EP1S25	672-pin BGA 672-pin FineLine BGA	16 (3)	8	4		
	780-pin FineLine BGA 1,020-pin FineLine BGA	20	8	4		
EP1S30	956-pin BGA 780-pin FineLine BGA 1,020-pin FineLine BGA	20	8	4		
EP1S40	956-pin BGA 1,020-pin FineLine BGA 1,508-pin FineLine BGA	20	8	4		
EP1S60	956-pin BGA 1,020-pin FineLine BGA 1,508-pin FineLine BGA	20	8	4		
EP1S80	956-pin BGA 1,508-pin FineLine BGA 1,923-pin FineLine BGA	20	8	4		

Notes to Table 2–27:

- See the Selectable I/O Standards in Stratix & Stratix GX Devices chapter in the Stratix Device Handbook, Volume 2 for V_{RFF} guidelines.
- (2) These packages have six groups in I/O banks 3 and 4 and six groups in I/O banks 7 and 8.
- (3) These packages have eight groups in I/O banks 3 and 4 and eight groups in I/O banks 7 and 8.
- (4) This package has nine groups in I/O banks 3 and 4 and nine groups in I/O banks 7 and 8.
- (5) These packages have three groups in I/O banks 3 and 4 and four groups in I/O banks 7 and 8.

A compensated delay element on each DQS pin automatically aligns input DQS synchronization signals with the data window of their corresponding DQ data signals. The DQS signals drive a local DQS bus in the top and bottom I/O banks. This DQS bus is an additional resource to the I/O clocks and is used to clock DQ input registers with the DQS signal.

Two separate single phase-shifting reference circuits are located on the top and bottom of the Stratix device. Each circuit is driven by a system reference clock through the CLK pins that is the same frequency as the DQS signal. Clock pins CLK [15..12] p feed the phase-shift circuitry on the top of the device and clock pins CLK [7..4] p feed the phase-shift circuitry on the bottom of the device. The phase-shifting reference circuit on the top of the device controls the compensated delay elements for all 10 DQS pins located at the top of the device. The phase-shifting reference circuit on the bottom of the device controls the compensated delay elements for all 10 DQS pins located on the bottom of the device. All 10 delay elements (DQS signals) on either the top or bottom of the device

I/O pin has an individual slew-rate control, allowing you to specify the slew rate on a pin-by-pin basis. The slew-rate control affects both the rising and falling edges.

Bus Hold

Each Stratix device I/O pin provides an optional bus-hold feature. The bus-hold circuitry can weakly hold the signal on an I/O pin at its last-driven state. Since the bus-hold feature holds the last-driven state of the pin until the next input signal is present, an external pull-up or pull-down resistor is not needed to hold a signal level when the bus is tri-stated.

Table 2–29 shows bus hold support for different pin types.

Table 2–29. Bus Hold Support				
Pin Type	Bus Hold			
I/O pins	✓			
CLK[150]				
CLK[0,1,2,3,8,9,10,11]				
FCLK	~			
FPLL[710]CLK				

The bus-hold circuitry also pulls undriven pins away from the input threshold voltage where noise can cause unintended high-frequency switching. You can select this feature individually for each I/O pin. The bus-hold output drives no higher than $V_{\rm CCIO}$ to prevent overdriving signals. If the bus-hold feature is enabled, the programmable pull-up option cannot be used. Disable the bus-hold feature when using opendrain outputs with the GTL+ I/O standard or when the I/O pin has been configured for differential signals.

The bus-hold circuitry uses a resistor with a nominal resistance (R_{BH}) of approximately 7 k Ω to weakly pull the signal level to the last-driven state. See the DC & Switching Characteristics chapter of the Stratix Device Handbook, Volume 1 for the specific sustaining current driven through this resistor and overdrive current used to identify the next-driven input level. This information is provided for each V_{CCIO} voltage level.

The bus-hold circuitry is active only after configuration. When going into user mode, the bus-hold circuit captures the value on the pin present at the end of configuration.

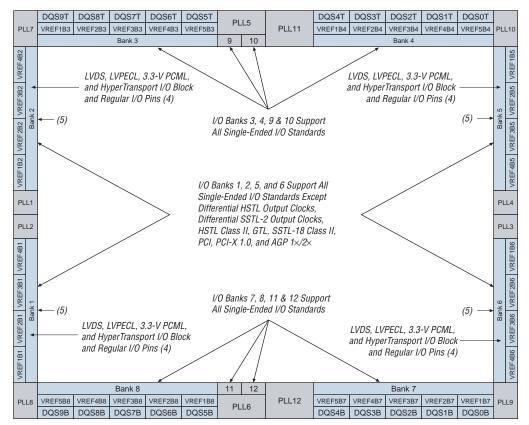


Figure 2–70. Stratix I/O Banks Notes (1), (2), (3)

Notes to Figure 2–70:

- (1) Figure 2–70 is a top view of the silicon die. This will correspond to a top-down view for non-flip-chip packages, but will be a reverse view for flip-chip packages.
- (2) Figure 2–70 is a graphic representation only. See the device pin-outs on the web (www.altera.com) and the Quartus II software for exact locations.
- (3) Banks 9 through 12 are enhanced PLL external clock output banks.
- (4) If the high-speed differential I/O pins are not used for high-speed differential signaling, they can support all of the I/O standards except HSTL Class I and II, GTL, SSTL-18 Class II, PCI, PCI-X 1.0, and AGP 1×/2×.
- (5) For guidelines for placing single-ended I/O pads next to differential I/O pads, see the Selectable I/O Standards in Stratix and Stratix GX Devices chapter in the Stratix Device Handbook, Volume 2.

JTAG Instruction	Instruction Code	Description
SAMPLE/PRELOAD	00 0000 0101	Allows a snapshot of signals at the device pins to be captured and examined during normal device operation, and permits an initial data pattern to be output at the device pins. Also used by the SignalTap II embedded logic analyzer.
EXTEST (1)	00 0000 0000	Allows the external circuitry and board-level interconnects to be tested by forcing a test pattern at the output pins and capturing test results at the input pins.
BYPASS	11 1111 1111	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation.
USERCODE	00 0000 0111	Selects the 32-bit USERCODE register and places it between the TDI and TDO pins, allowing the USERCODE to be serially shifted out of TDO.
IDCODE	00 0000 0110	Selects the IDCODE register and places it between TDI and TDO, allowing the IDCODE to be serially shifted out of TDO.
HIGHZ (1)	00 0000 1011	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation, while tri-stating all of the I/O pins.
CLAMP (1)	00 0000 1010	Places the 1-bit bypass register between the TDI and TDO pins, which allows the BST data to pass synchronously through selected devices to adjacent devices during normal device operation while holding I/O pins to a state defined by the data in the boundary-scan register.
ICR instructions		Used when configuring an Stratix device via the JTAG port with a MasterBlaster™, ByteBlasterMV™, or ByteBlaster™ II download cable, or when using a Jam File or Jam Byte-Code File via an embedded processor or JRunner.
PULSE_NCONFIG	00 0000 0001	Emulates pulsing the nCONFIG pin low to trigger reconfiguration even though the physical pin is unaffected.
CONFIG_IO	00 0000 1101	Allows configuration of I/O standards through the JTAG chain for JTAG testing. Can be executed before, after, or during configuration. Stops configuration if executed during configuration. Once issued, the CONFIG_IO instruction will hold nSTATUS low to reset the configuration device. nSTATUS is held low until the device is reconfigured.
SignalTap II instructions		Monitors internal device operation with the SignalTap II embedded logic analyzer.

Note to Table 3–1:

(1) Bus hold and weak pull-up resistor features override the high-impedance state of HIGHZ, CLAMP, and EXTEST.

The Stratix device instruction register length is 10 bits and the USERCODE register length is 32 bits. Tables 3–2 and 3–3 show the boundary-scan register length and device IDCODE information for Stratix devices.

Table 3–2. Stratix Boundary-Scan Register Length				
Device Boundary-Scan Register Le				
EP1S10	1,317			
EP1S20	1,797			
EP1S25	2,157			
EP1S30	2,253			
EP1S40	2,529			
EP1S60	3,129			
EP1S80	3,777			

Table 3–3	Table 3–3. 32-Bit Stratix Device IDCODE							
	IDCODE (32 Bits) (1)							
Device	Version (4 Bits)	Part Number (16 Bits)	Manufacturer Identity (11 Bits)	LSB (1 Bit) (2)				
EP1S10	0000	0010 0000 0000 0001	000 0110 1110	1				
EP1S20	0000	0010 0000 0000 0010	000 0110 1110	1				
EP1S25	0000	0010 0000 0000 0011	000 0110 1110	1				
EP1S30	0000	0010 0000 0000 0100	000 0110 1110	1				
EP1S40	0000	0010 0000 0000 0101	000 0110 1110	1				
EP1S60	0000	0010 0000 0000 0110	000 0110 1110	1				
EP1S80	0000	0010 0000 0000 0111	000 0110 1110	1				

Notes to Tables 3-2 and 3-3:

- (1) The most significant bit (MSB) is on the left.
- (2) The IDCODE's least significant bit (LSB) is always 1.

Stratix External I/O Timing

These timing parameters are for both column IOE and row IOE pins. In EP1S30 devices and above, you can decrease the t_{SU} time by using the FPLLCLK, but may get positive hold time in EP1S60 and EP1S80 devices. You should use the Quartus II software to verify the external devices for any pin.

Tables 4–55 through 4–60 show the external timing parameters on column and row pins for EP1S10 devices.

Table 4–55. EP1S10 External I/O Timing on Column Pins Using Fast Regional Clock Networks Note (1)									
Parameter	-5 Spee	d Grade	-6 Spee	d Grade	-7 Spee	d Grade	-8 Spee	d Grade	11
	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{INSU}	2.238		2.325		2.668		NA		ns
t _{INH}	0.000		0.000		0.000		NA		ns
t _{OUTCO}	2.240	4.549	2.240	4.836	2.240	5.218	NA	NA	ns
t _{XZ}	2.180	4.423	2.180	4.704	2.180	5.094	NA	NA	ns
t _{ZX}	2.180	4.423	2.180	4.704	2.180	5.094	NA	NA	ns

Table 4–56. l	Table 4–56. EP1S10 External I/O Timing on Column Pins Using Regional Clock Networks Note (1)									
	-5 Spee	d Grade	-6 Spee	d Grade	-7 Spee	d Grade	-8 Spee	d Grade		
Parameter	Min	Max	Min	Max	Min	Max			Unit	
t _{INSU}	1.992		2.054		2.359		NA		ns	
t _{INH}	0.000		0.000		0.000		NA		ns	
t _{оитсо}	2.395	4.795	2.395	5.107	2.395	5.527	NA	NA	ns	
t _{XZ}	2.335	4.669	2.335	4.975	2.335	5.403	NA	NA	ns	
t _{ZX}	2.335	4.669	2.335	4.975	2.335	5.403	NA	NA	ns	
t _{INSUPLL}	0.975		0.985		1.097		NA		ns	
t _{INHPLL}	0.000		0.000		0.000		NA	NA	ns	
t _{OUTCOPLL}	1.262	2.636	1.262	2.680	1.262	2.769	NA	NA	ns	
t _{XZPLL}	1.202	2.510	1.202	2.548	1.202	2.645	NA	NA	ns	
t _{ZXPLL}	1.202	2.510	1.202	2.548	1.202	2.645	NA	NA	ns	

Table 4-95. E	Table 4–95. EP1S80 External I/O Timing on Row Pins Using Regional Clock Networks Note (1)								
Parameter	-5 Spee	d Grade	-6 Spee	d Grade	-7 Spee	d Grade	-8 Spee	d Grade	Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
t _{INSU}	2.295		2.454		2.767		NA		ns
t _{INH}	0.000		0.000		0.000		NA		ns
t _{оитсо}	2.917	5.732	2.917	6.148	2.917	6.705	NA	NA	ns
t _{XZ}	2.944	5.786	2.944	6.204	2.944	6.773	NA	NA	ns
t _{ZX}	2.944	5.786	2.944	6.204	2.944	6.773	NA	NA	ns
t _{INSUPLL}	1.011		1.161		1.372		NA		ns
t _{INHPLL}	0.000		0.000		0.000		NA		ns
t _{OUTCOPLL}	1.808	3.169	1.808	3.209	1.808	3.233	NA	NA	ns
t _{XZPLL}	1.835	3.223	1.835	3.265	1.835	3.301	NA	NA	ns
t _{ZXPLL}	1.835	3.223	1.835	3.265	1.835	3.301	NA	NA	ns

Table 4-96.	Table 4–96. EP1880 External I/O Timing on Rows Using Pin Global Clock Networks Note (1)								
Cumbal	-5 Spee	d Grade	-6 Spee	d Grade	-7 Spee	d Grade	-8 Spee	d Grade	Heit
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Unit
t _{INSU}	1.362		1.451		1.613		NA		ns
t _{INH}	0.000		0.000		0.000		NA		ns
t _{outco}	3.457	6.665	3.457	7.151	3.457	7.859	NA	NA	ns
t _{XZ}	3.484	6.719	3.484	7.207	3.484	7.927	NA	NA	ns
t _{ZX}	3.484	6.719	3.484	7.207	3.484	7.927	NA	NA	ns
t _{INSUPLL}	0.994		1.143		1.351		NA		ns
t _{INHPLL}	0.000		0.000		0.000		NA		ns
t _{OUTCOPLL}	1.821	3.186	1.821	3.227	1.821	3.254	NA	NA	ns
t _{XZPLL}	1.848	3.240	1.848	3.283	1.848	3.322	NA	NA	ns
t _{ZXPLL}	1.848	3.240	1.848	3.283	1.848	3.322	NA	NA	ns

Note to Tables 4–91 to 4–96:

⁽¹⁾ Only EP1S25, EP1S30, and EP1S40 devices have the -8 speed grade.

Table 4–117. Stratix Maximum Input Clock Rate for CLK[7..4] & CLK[15..12] Pins in Wire-Bond Packages (Part 2 of 2)

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
GTL+	250	200	200	MHz
SSTL-3 Class I	300	250	250	MHz
SSTL-3 Class II	300	250	250	MHz
SSTL-2 Class I	300	250	250	MHz
SSTL-2 Class II	300	250	250	MHz
SSTL-18 Class I	300	250	250	MHz
SSTL-18 Class II	300	250	250	MHz
1.5-V HSTL Class I	300	180	180	MHz
1.5-V HSTL Class II	300	180	180	MHz
1.8-V HSTL Class I	300	180	180	MHz
1.8-V HSTL Class II	300	180	180	MHz
3.3-V PCI	422	390	390	MHz
3.3-V PCI-X 1.0	422	390	390	MHz
Compact PCI	422	390	390	MHz
AGP 1×	422	390	390	MHz
AGP 2×	422	390	390	MHz
CTT	250	180	180	MHz
Differential 1.5-V HSTL C1	300	180	180	MHz
LVPECL (1)	422	400	400	MHz
PCML (1)	215	200	200	MHz
LVDS (1)	422	400	400	MHz
HyperTransport technology (1)	422	400	400	MHz

Table 4–118. Stratix Maximum Input Clock Rate for CLK[0, 2, 9, 11] Pins & FPLL[10..7]CLK Pins in Wire-Bond Packages (Part 1 of 2)

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
LVTTL	422	390	390	MHz
2.5 V	422	390	390	MHz
1.8 V	422	390	390	MHz
1.5 V	422	390	390	MHz

Table 4–121. Stratix Maximum Output Clock Rate (Using I/O Pins) for PLL[1, 2, 3, 4] Pins in Flip-Chip Packages

I/O Standard	-5 Speed Grade	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
LVTTL	400	350	300	300	MHz
2.5 V	400	350	300	300	MHz
1.8 V	400	350	300	300	MHz
1.5 V	350	300	300	300	MHz
LVCMOS	400	350	300	300	MHz
GTL	200	167	125	125	MHz
GTL+	200	167	125	125	MHz
SSTL-3 Class I	167	150	133	133	MHz
SSTL-3 Class II	167	150	133	133	MHz
SSTL-2 Class I	150	133	133	133	MHz
SSTL-2 Class II	150	133	133	133	MHz
SSTL-18 Class I	150	133	133	133	MHz
SSTL-18 Class II	150	133	133	133	MHz
1.5-V HSTL Class I	250	225	200	200	MHz
1.5-V HSTL Class II	225	225	200	200	MHz
1.8-V HSTL Class I	250	225	200	200	MHz
1.8-V HSTL Class II	225	225	200	200	MHz
3.3-V PCI	250	225	200	200	MHz
3.3-V PCI-X 1.0	225	225	200	200	MHz
Compact PCI	400	350	300	300	MHz
AGP 1×	400	350	300	300	MHz
AGP 2×	400	350	300	300	MHz
CTT	300	250	200	200	MHz
LVPECL (2)	717	717	500	500	MHz
PCML (2)	420	420	420	420	MHz
LVDS (2)	717	717	500	500	MHz
HyperTransport technology (2)	420	420	420	420	MHz

PLL Specifications

Tables 4–127 through 4–129 describe the Stratix device enhanced PLL specifications.

Table 4–127.	Enhanced PLL Specifications for -5 Sp	eed Gra	des (Part 1 of 2)	
Symbol	Parameter	Min	Тур	Max	Unit
f _{IN}	Input clock frequency	3 (1), (2)		684	MHz
f _{INPFD}	Input frequency to PFD	3		420	MHz
f _{INDUTY}	Input clock duty cycle	40		60	%
f _{EINDUTY}	External feedback clock input duty cycle	40		60	%
t _{INJITTER}	Input clock period jitter			±200 (3)	ps
t _{EINJITTER}	External feedback clock period jitter			±200 (3)	ps
t _{FCOMP}	External feedback clock compensation time (4)			6	ns
f _{OUT}	Output frequency for internal global or regional clock	0.3		500	MHz
f _{OUT_EXT}	Output frequency for external clock (3)	0.3		526	MHz
t _{OUTDUTY}	Duty cycle for external clock output (when set to 50%)	45		55	%
t _{JITTER}	Period jitter for external clock output (6)			±100 ps for >200-MHz outclk ±20 mUI for <200-MHz outclk	ps or mUI
t _{CONFIG5,6}	Time required to reconfigure the scan chains for PLLs 5 and 6			289/f _{SCANCLK}	
t _{CONFIG11,12}	Time required to reconfigure the scan chains for PLLs 11 and 12			193/f _{SCANCLK}	
t _{SCANCLK}	scanclk frequency (5)			22	MHz
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays) (7)			100	μs
t _{LOCK}	Time required to lock from end of device configuration	10		400	μs
f _{VCO}	PLL internal VCO operating range	300		800 (8)	MHz
t _{LSKEW}	Clock skew between two external clock outputs driven by the same counter		±50		ps

Table 4-12	9. Enhanced PLL Specifications for -7	Speed !	Grade	(Part 2 of 2)	
Symbol	Parameter	Min	Тур	Max	Unit
t _{OUTDUTY}	Duty cycle for external clock output (when set to 50%)	45		55	%
t _{JITTER}	Period jitter for external clock output (6)			±100 ps for >200-MHz outclk ±20 mUI for <200-MHz outclk	ps or mUI
t _{CONFIG5,6}	Time required to reconfigure the scan chains for PLLs 5 and 6			289/f _{SCANCLK}	
t _{CONFIG11,12}	Time required to reconfigure the scan chains for PLLs 11 and 12			193/f _{SCANCLK}	
t _{SCANCLK}	scanclk frequency (5)			22	MHz
t _{DLOCK}	Time required to lock dynamically (after switchover or reconfiguring any non-post-scale counters/delays) (7) (11)	(9)		100	μs
t _{LOCK}	Time required to lock from end of device configuration (11)	10		400	μs
f _{VCO}	PLL internal VCO operating range	300		600 (8)	MHz
t _{LSKEW}	Clock skew between two external clock outputs driven by the same counter		±50		ps
t _{SKEW}	Clock skew between two external clock outputs driven by the different counters with the same settings		±75		ps
f _{SS}	Spread spectrum modulation frequency	30		150	kHz
% spread	Percentage spread for spread spectrum frequency (10)	0.5		0.6	%
t _{ARESET}	Minimum pulse width on areset signal	10			ns

Table 4–130. Enhanced PLL Specifications for -8 Speed Grade (Part 1 of 3)							
Symbol	Parameter	Min	Тур	Max	Unit		
f _{IN}	Input clock frequency	3 (1), (2)		480	MHz		
f _{INPFD}	Input frequency to PFD	3		420	MHz		
f _{INDUTY}	Input clock duty cycle	40		60	%		
f _{EINDUTY}	External feedback clock input duty cycle	40		60	%		
t _{INJITTER}	Input clock period jitter			±200 (3)	ps		